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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

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Application Number	Unknown
Filing Date	June 28, 2001
First Named Inventor	Yoshihiko Toyoda
Group Art Unit	Unknown
Examiner Name	Unknown
Attorney Docket Number	401265/FUKAMI

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Examiner Initials	Doc. No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number (s), publisher, city and/or country where published.	Translation	
			Yes	No**
CSA	A 2	E. RICHARD et al.; "Roles of additives during filing process of damascene structures with Electrochemical Deposited Copper", <u>ADMETA</u> , pp. 135-136, October 14-15, 1999.		
UA	A 3	J. REID et al.; "Process and Material Variables Influencing IC Feature Fill Using Electroplated Copper"; <u>ADMETA</u> , pp. 35-36, 1999.		
UA	A 4	"IBM's Impact on Development of Cu Plating Started Last April in Japan Aspect Ratio Matters...", <u>Monthly Semiconductor World</u> , December 1997.		X*

Date Considered

- * A concise statement of relevance is being submitted in lieu of a translation. 37 CFR 1.98(a)(3).
+ An English-language equivalent/patent, or an English-language abstract, or an English-language version of the search report or action by a foreign patent office in a counterpart foreign application indicating the degree of relevance found by the foreign office is being submitted in lieu of a concise explanation of relevance under 37 CFR 1.98(a)(3).